| ASSOCIATION CONNECTING<br>ASSOCIATION CONNECTING<br>ELECTRONICS INDUSTRIES®<br>international and Par | PC. Bannockł                      | ourn, Illinois, A          | Il rights reserved untions. | under both              | This docume<br>level parts, t | ent is a declaration en declaration | on of the sub<br>compasses             | bstances w<br>all lower | vithin the manufactu<br>level materials for v | rer listed which the r                  | tem. Note:<br>nanufacture       | if the item is an as<br>er has engineering | sembly with low responsibility. |  |
|--|-----------------------------------|----------------------------|-----------------------------|-------------------------|-------------------------------|---|--|-------------------------|---|---|---------------------------------|--|---------------------------------|--|
|  |                                   |                            |                             | Form Type<br>Distribute |                               |   |  |                         | ials and Mfg Information                      |   |                                 |  |                                 |  |
| upplier Information  |                                   |                            |                             |                         |                               |   |  |                         |   |   |                                 |  |                                 |  |
| Company name* Con  |                                   |                            | Company unique ID           |                         |                               | Unique ID Authority   |  |                         |   | Respon                                  | Response Date*                  |  |                                 |  |
| onsemi   |                                   |                            |                             |                         |                               |   |  |                         |   | 2023-00                                 | 2023-06-08                      |  |                                 |  |
| Contact Name Title - Contact   |                                   |                            | ct                          |                         |                               | Phone - Contact*  |  |                         |   | Email -                                 | Email - Contact*                |  |                                 |  |
| Product-Env-Stewards Product En  |                                   |                            | Enviro Compliance           |                         |                               | NA  |  |                         |   | Produ                                   | Product-Env-Stewards@onsemi.com |  |                                 |  |
| Authorized Representative* Title - Repres  |                                   |                            | esentative                  |                         |                               | Phone - Representative*   |  |                         |   | Email -                                 | Email - Representative*         |  |                                 |  |
| Product-Env-Stewards Product   |                                   |                            | roduct Enviro Compliance    |                         |                               | NA  |  |                         |   | Product-Env-Stewards@onsemi.com         |                                 |  |                                 |  |
| Requester Item Number  | em Number Mfr Item Num            |                            | Number Mfr Item Name        |                         |                               | Effective Date  | ective Date Version Manufacturing Site |                         | anufacturing Site                             |   | Weight*                         | UOM  | Unit Type                       |  |
|  | NCP125                            | NCP1252DDR2G CM PWM Contro |                             | oller                   |                               | 2023-06-08  |  | Cl                      | CNW   |   | 71.99                           | mg   | Each                            |  |
| Ianufacturing Proccess Informa   | tion                              |                            | ·                           |                         |                               | ·   |  |                         |   |   |                                 |  |                                 |  |
| Terminal Plating / Grid Array M  | Grid Array Material Terminal Base |                            | loy J-STD-020 MSL Rating    |                         | L Rating                      | Peak Proce  | Peak Process Body Temperature Max Time |                         | Max Time at Peal                              | eak Temperature Number of Reflow Cycles |                                 | les  |                                 |  |
| Matte Tin (Sn) - annealed CU All   |                                   | CU Alloy                   | 1                           |                         |                               | 260 C 30  |  | 30                      | seconds 3                                     |   |                                 |  |                                 |  |
| omments  |                                   |                            |                             |                         |                               |   |  |                         |   |   |                                 |  |                                 |  |
| vel 1 - maximum time at peak temperatu   | ure during so                     | ldering is 10-3            | 0 seconds                   |                         |                               |   |  |                         |   |   |                                 |  |                                 |  |
| or more information regarding material   | composition                       | please refer to            | page 3                      |                         |                               |   |  |                         |   |   |                                 |  |                                 |  |

| RoHS Material Composition Declaration  |  |  |   | Declaration Type *                              | Detailed  |  |  |  |  |  |  |
|--|--|--|---|---|---|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP). |  |   |   |   |  |  |  |  |  |  |
| cadmium, hexavalentchromium, polybrominate<br>contains a RoHS restricted substance inexcess<br>encompass all such components. Supplier certif<br>as of the date that Supplier completes this form<br>Company acknowledges that Supplier may hav<br>independently verified information provided by<br>certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip<br>of an applicable quantity limit, please ir<br>ies that it gathered the information it pro-<br>.Supplier acknowledges that Company<br>e relied on informationprovided by othe<br>v others, Supplier agrees that, at a minin<br>and the Supplier enter into a written agre<br>pource of the Supplier's liability and the   | henyl ethers (each a "<br>ndicate below which, i<br>ovides in this form us<br>will rely on this certifiers<br>in completing this<br>num, itssuppliers have<br>eement with respect to<br>Company's remedies | RoHS restricted substance") in exce<br>if any, RoHS exemption you believe<br>ing appropriate methods to ensure if<br>ication in determining the complian<br>form, and that Supplier may not have<br>e provided certifications regarding the<br>to the identified part, the terms and cc<br>for issues that arise regarding inform | ce of its products with European Union membe    | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>l correct to the best of its knowledge and belief,<br>r state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>tions are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |  |
| RoHS Declaration * 1 - Item(s)   | does not contain RoHS restricted substa  | on above   | Supplier Acceptance   | * Accepted                                      |   |  |  |  |  |  |  |
| Exemption: If the declared item does not con applicable exemptions.  | ntain RoHS restricted substances per   | the definition above   | except for defined RoHS exempti   | ons, then select the corresponding response i   | n the RoHS Declaration above and choose all   |  |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU   |  |   |   |   |  |  |  |  |  |  |
| Declaration Signature  |  |  |   |   |   |  |  |  |  |  |  |
| Instructions: Complete all of the required fin<br>Requester) and click on Submit Form to have  | elds on all pages of this form. Select the form returned to the Requester  | he "Accepted" on th  | e Supplier Acceptance drop-down   | . This will display the signature area. Digital | lly sign the declaration (if required by the  |  |  |  |  |  |  |
| Supplier Digital Signature Ra  | stislav Drska  | Le   |   |   |   |  |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level    | Substance                  | CAS              | Exempt | Weight  | Unit of Measure |
|----------------------|--------|-----------------|----------|----------------------------|------------------|--------|---------|-----------------|
| Die                  | 1.33   | mg              | Supplier | Silicon (Si)               | 7440-21-3        |        | 1.33    | mg              |
| Die Attach           | 2.4    | mg              |          | Epoxy resin                | proprietary data |        | 0.06    | mg              |
|                      |        |                 | Supplier | Silver (Ag)                | 7440-22-4        |        | 1.92    | mg              |
|                      |        |                 | Supplier | Polybutadiene polymer      | Proprietary Data |        | 0.156   | mg              |
|                      |        |                 | Supplier | Acrylic resins             | Proprietary Data |        | 0.264   | mg              |
| Lead Frame           | 37.61  | mg              | Supplier | Silver (Ag)                | 7440-22-4        |        | 0.2257  | mg              |
|                      |        |                 | Supplier | Zinc (Zn)                  | 7440-66-6        |        | 0.0451  | mg              |
|                      |        |                 | Supplier | Iron (Fe)                  | 7439-89-6        |        | 0.8838  | mg              |
|                      |        |                 | Supplier | Copper (Cu)                | 7440-50-8        |        | 36.4441 | mg              |
|                      |        |                 | Supplier | Phosphorus (P)             | 7723-14-0        |        | 0.0113  | mg              |
| Mold Compound-Black  | 28.58  | mg              | Supplier | Carbon Black (C)           | 1333-86-4        |        | 0.1429  | mg              |
|                      |        |                 | Supplier | Fused Silica (SiO2)        | 60676-86-0       |        | 25.0075 | mg              |
|                      |        |                 | Supplier | Ortho-Cresol Novolac Resin | 29690-82-2       |        | 1.7148  | mg              |
|                      |        |                 | Supplier | Phenolic Resin (Novolac)   | 9003-35-4        |        | 1.7148  | mg              |
| Plating              | 1.89   | mg              | Supplier | Tin (Sn)                   | 7440-31-5        |        | 1.89    | mg              |
| Wire Bond - Cu       | 0.18   | mg              | Supplier | Palladium (Pd)             | 7440-05-3        |        | 0.0029  | mg              |
|                      |        |                 | Supplier | Copper (Cu)                | 7440-50-8        |        | 0.1771  | mg              |

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).